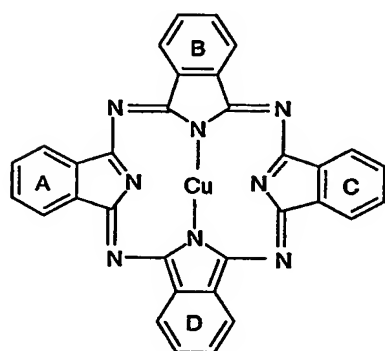


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What is claimed is:

1. A photosensitive resin composition comprising
as a component (A) a green colorant of the formula



(1)

in which the rings A, B, C and D are substituted by hydroxy or by the moiety

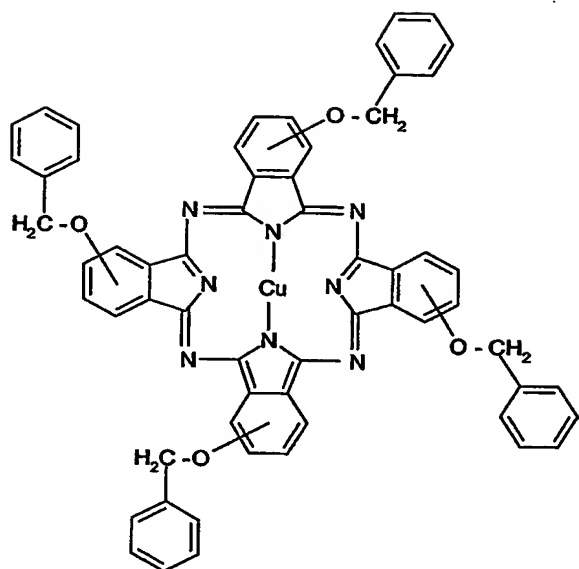
$-\text{O}-(\text{CR}_1\text{R}_2)_n-$ , wherein R_1 is hydrogen or $\text{C}_1\text{-C}_4\text{-Alkyl}$, R_2 is hydrogen or $\text{C}_1\text{-C}_4\text{-Alkyl}$,

n is 0, 1, 2 or 3 and the ring E is unsubstituted or substituted by $\text{C}_1\text{-C}_6\text{alkyl}$, $\text{C}_1\text{-C}_6\text{alkoxy}$, hydroxy, NHCOR_3 , NHSO_2R_4 or SO_2NHR_5 , wherein R_3 is $\text{C}_1\text{-C}_4\text{-Alkyl}$ or phenyl, R_4 is $\text{C}_1\text{-C}_4\text{-Alkyl}$ or phenyl and R_5 is $\text{C}_1\text{-C}_4\text{-Alkyl}$ or phenyl,

- b) as a component (B) an alkali soluble oligomer or polymer (reactive or unreactive),
 - c) as a component (C) a polymerizable monomer,
 - d) as a component (D) a photoinitiator,
 - e) as a component (E) an epoxy compound,
- and also, if desired,
- f) as a component (F) further additives.

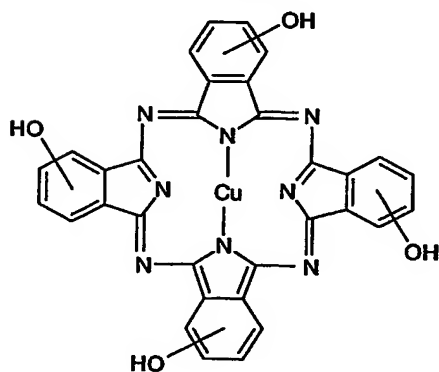
2. A photosensitive resin composition according to claim 1, wherein the component (A) is the colorant of formula

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(2).

3. A photosensitive resin composition according to claim 1, wherein the component (A) is the colorant of formula



(3).

4. Solder resist process using the photosensitive resin composition according to any one of claims 1 to 3, which process comprises the steps of

- (1) mixing the components (A) to (E) and if desired (F),
- (2) applying the resulting composition to the substrate ("coating of the substrate"),
- (3) evaporating of the solvent, if present, at a temperature between 80-90°C,
- (4) exposing the coated substrate to irradiation through a negative mask or by a direct laser imaging,

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(5) developing the irradiated sample by washing with aqueous alkaline solution and thereby removing the uncured areas,

and

(6) thermally curing the sample at a temperature about 150°C, thereby initiating the cross-linking between the carboxylic acid and the epoxy component.

5. Coated substrate obtained by the process according to claim 4.

6. Substrate coated with the photosensitive resin composition according to any of claims 1 to 3.